



Rambus to Address Memory Challenges for Multi-Core Computing at Intel Developer Forum 2009

Company to Feature Sony PlayStation(R)3 Slim in XDR(TM) Memory Product Showcase

SAN FRANCISCO, Sep 21, 2009 (BUSINESS WIRE) -- Rambus Inc. (NASDAQ: RMBS):

Who: Rambus Inc. (NASDAQ: RMBS)

Where: Intel Developer Forum
Booth #101
Moscone Center West
San Francisco, California

When: September 22-24, 2009

Join [Rambus Inc.](#), one of the world's premier technology licensing companies specializing in high-speed memory architectures, at the Intel Developer Forum 2009 for a presentation on memory architectures for multi-core computing. In addition, Rambus will exhibit end-user products utilizing its award-winning XDR(TM) memory architecture.

Rambus Presentation

Tuesday, September 22, 11:15 a.m. PDT

"Memory Architectures for Multi-core Computing in Next-generation PCs and Smartphones"

Presented by Craig Hampel, Rambus Fellow

Moscone Center West, Room 2005

Mr. Hampel will address memory architecture optimizations that can support the many threads and workloads handled by multi-core processors in next-generation PCs and Smartphones. As part of his talk, Mr. Hampel will discuss innovations that can significantly improve memory throughput and reduce power consumption.

Rambus Demos and Displays

The XDR Product Showcase will exhibit low-power, power-efficient, and multi-core designs in some of today's most compelling electronics products including:

- PlayStation(R)3 (PS3(TM)) Slim live demo and open demo board, featuring the XDR memory architecture. The Rambus XDR memory interface and FlexIO(TM) processor bus on the Cell Broadband Engine(TM) enable an unprecedented aggregate bandwidth of over 65GB/s in the PS3.
- TI DLP(R) projector open demo board, featuring the XDR memory architecture. This architecture, including XDR DRAM, XDR memory controller (XMC), XDR IO cell (XIO), and XDR clock generator (XCG), delivers memory bandwidth up to 8.0GB/s in the latest generation of HD front projectors.
- PC-over-IP(R) (PCoIP) open demo boards of both Host and Portal products powered by Teradici's TERA processors and the XDR memory architecture.
- Toshiba Qosmio(R) laptop PC featuring the SpursEngine video processor and XDR DRAM.

In addition to the XDR Product Showcase, Rambus will demonstrate its latest technology developments in the areas of computing, graphics, and mobile applications.

Mobile Memory

Silicon test demonstration of a collection of high-bandwidth, low-power memory technologies targeted at achieving data rates of 4.3Gbps at best-in-class power efficiency. With this performance, designers could realize more than 17GB/s of memory bandwidth from a single mobile DRAM device.

Graphics Memory

Silicon demonstration of a complete XDR(TM) memory system running at data rates up to 7.2Gbps with superior power efficiency. The XIO memory controller demonstrates bi-modal operation with support for both XDR DRAM as well as next-generation XDR2 DRAM.

Computing Memory

Video demonstration of a set of innovations that can advance computing main memory beyond current DDR3 data rate limits to 3200Mbps. Key innovations include: Near Ground Signaling -- supports high performance at greatly reduced IO power; FlexClocking(TM) Architecture -- introduced in Rambus' Mobile Memory Initiative, reduces clocking power by eliminating the need for a DLL or PLL on the DRAM; Module Threading -- increases memory efficiency and reduces DRAM core power, and when combined with Near Ground Signaling and FlexClocking technology, can cut total memory system power by over 40 percent.

Rambus will also showcase the recently-announced module prototype co-developed with Kingston Memory, using DDR3 DRAM technology and Rambus' Module Threading technology. In this prototype, initial silicon results show an improvement in data throughput of up to 50 percent, while reducing power consumption by 20 percent compared to conventional modules.

For more information on the XDR memory architecture, please visit www.rambus.com/xdr.

About Rambus Inc.

Rambus is one of the world's premier technology licensing companies specializing in the invention and design of high-speed memory architectures. Since its founding in 1990, the Company's patented innovations, breakthrough technologies and renowned integration expertise have helped industry-leading chip and system companies bring superior products to market. Rambus' technology and products solve customers' most complex chip and system-level interface challenges enabling unprecedented performance in computing, communications and consumer electronics applications. Rambus licenses both its world-class patent portfolio as well as its family of leadership and industry-standard interface products. Headquartered in Los Altos, California, Rambus has regional offices in North Carolina, India, Germany, Japan, and Taiwan. Additional information is available at www.rambus.com.

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